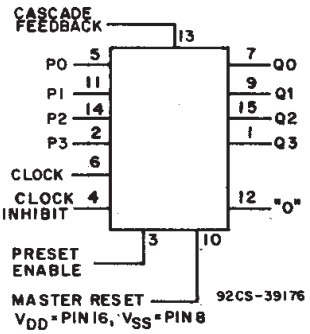
TEXAS INSTRUMENTS
Data sheet acquired from Harris Semiconductor
SCHS079C – Revised October 2003

NOT RECOMMENDED FOR NEW DESIGNS

CD4522B Types

Advance Information/ Preliminary Data



FUNCTIONAL DIAGRAM

CMOS Programmable BCD Divide-by-"N" Counter

High-Voltage Types (20-Volt Rating)

Features:

- *Internally synchronous for high internal and external speeds.*
- *Logic edge-clocked design — increments on positive Clock transition or on negative Clock Inhibit transition.*
- *100% tested for quiescent current at 20-V.*
- *5-V, 10-V, and 15-V parametric ratings.*
- *Standard symmetrical output characteristics.*
- *Maximum input current of 1 μA at 18 V over full package-temperature range: 100 nA at 18 V and 25° C.*
- *Meets all requirements of JEDEC Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices."*

■ CD4522B programmable BCD counter has a decoded "0" state output for divide-by-N applications. In single stage operation the "0" output is tied to the Preset Enable input. The Cascade Feedback allows multiple stage divide-by-N operation without the need for external gating. A HIGH on the Clock Inhibit disables the pulse-counting function. A HIGH on the Master Reset asynchronously resets the divide-by-N operation. The output is presented in BCD format.

The CD4522B-series types are supplied in 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (M, M96, MT, and NSR suffixes), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).

Applications:

- *Frequency synthesizers*
- *Phase-locked loops*
- *Programmable down counters*
- *Programmable frequency dividers*

3 COMMERCIAL CMOS HIGH VOLTAGE ICs

MAXIMUM RATINGS, *Absolute-Maximum Values:*

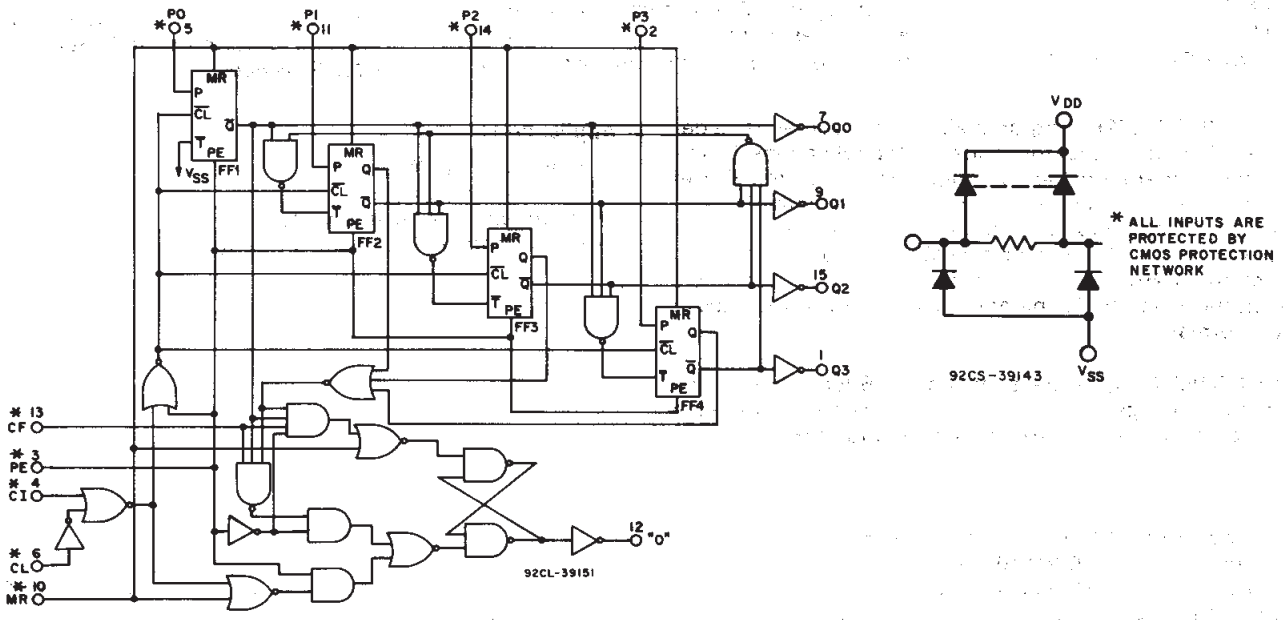
DC SUPPLY-VOLTAGE RANGE, (V_{DD})
(Voltages referenced to V_{SS} Terminal) ..... -0.5V to +20V
INPUT VOLTAGE RANGE, ALL INPUTS ..... -0.5V to V_{DD} +0.5V
DC INPUT CURRENT, ANY ONE INPUT ..... ±10mA
POWER DISSIPATION PER PACKAGE (P_D):
For T_A = -55°C to +100°C 500mW
For T_A = +100°C to +125°C ..... Derate Linearity at 12mW/°C to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR
FOR T_A = FULL PACKAGE-TEMPERATURE RANGE (All Package Types) 100mW
OPERATING-TEMPERATURE RANGE (T_A) ..... -55°C to +125°C
STORAGE TEMPERATURE RANGE (T_{stg}) ..... -65°C to +150°C
LEAD TEMPERATURE (DURING SOLDERING):
At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max ..... +265°C

TRUTH TABLES

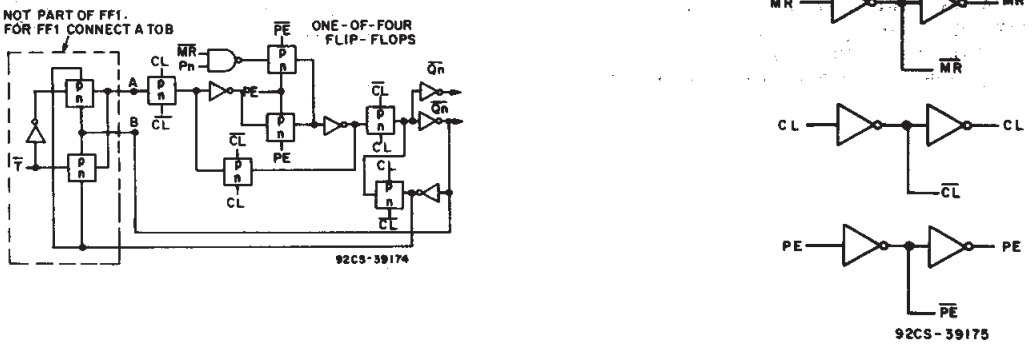
CLOCK	CLOCK INHIBIT	PRESET ENABLE	MASTER RESET	ACTION
0	0	0	0	No Count
⌒	0	0	0	Count Down
X	1	0	0	No Count
1	⌒	0	0	Count Down
X	X	1	0	Preset
X	X	X	1	Reset

X = Don't Care

Count	OUTPUTS			
	Q_0	Q_1	Q_2	Q_3
0	0	0	0	0
1	1	0	0	0
2	0	1	0	0
3	1	1	0	0
4	0	0	1	0
5	1	0	1	0
6	0	1	1	0
7	1	1	1	0
8	0	0	0	1
9	1	0	0	1



a. Basic diagram.



b. Flip-flop detail.

Fig. 1 - Logic diagram for the CD4522B.

RECOMMENDED OPERATING CONDITIONS at T_A = 25°C, except as noted.

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTICS	V_{DD} (V)	LIMITS		UNITS
		Min.	Max.	
Supply-Voltage Range (For T_A = Full Package-Temperature Range		3	18	V
Pulse Width:				
Clock, $tw_{(CC)}$	5	250	—	ns
	10	100	—	
	15	80	—	
Preset Enable, $tw_{(CC)}$	5	250	—	ns
	10	100	—	
	15	80	—	
Master Reset, $tw_{(MR)}$	5	350	—	ns
	10	250	—	
	15	200	—	
Clock Frequency, f_{CL}	5	—	1.5	MHz
	10	—	3.0	
	15	—	4.0	
Clock Rise and Fall Time t_{rCL}, t_{fCL}	5	—	15	μs
	10	—	15	
	15	—	15	
Preset Enable Set-up Time, t_{su}	5	0	—	ns
	10	0	—	
	15	0	—	
Preset Enable Hold Time, t_h	5	75	—	ns
	10	25	—	
	15	20	—	
Master Reset Removal Time, t_{rem}	5	130	—	ns
	10	50	—	
	15	30	—	

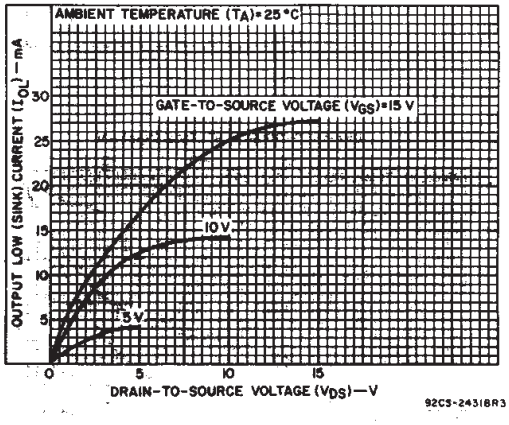


Fig. 2 — Typical output low (sink) current characteristics.

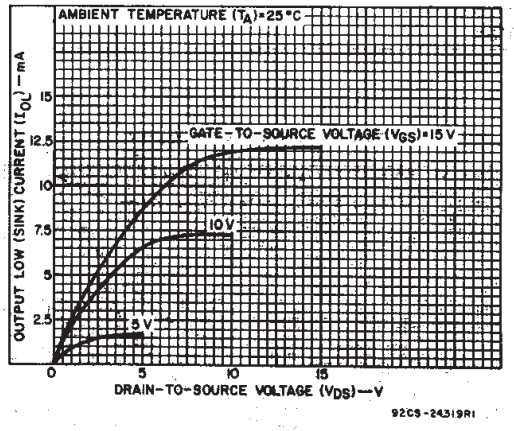


Fig. 3 — Minimum output low (sink) current characteristics.

STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
								+25			
	V_O (V)	V_{IN} (V)	V_{DD} (V)	-55	-40	+85	+125	Min.	Typ.	Max.	
Quiescent Device Current, I_{DD} Max.	—	0, 5	5	5	5	150	150	—	0.04	5	μA
	—	0, 10	10	10	10	300	300	—	0.04	10	
	—	0, 15	15	20	20	600	600	—	0.04	20	
	—	0, 20	20	100	100	3000	3000	—	0.08	100	
Output Low (Sink) Current I_{OL} Min.	0.4	0, 5	5	0.64	0.61	0.42	0.36	0.51	1	—	mA
	0.5	0, 10	10	1.6	1.5	1.1	0.9	1.3	2.6	—	
	1.5	0, 15	15	4.2	4	2.8	2.4	3.4	6.8	—	
Output High (Source) Current, I_{OH} Min.	4.6	0, 5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	—	
	2.5	0, 5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	—	
	9.5	0, 10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	—	
	13.5	0, 15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	—	
Output Voltage: Low-Level, V_{OL} Max.	—	0, 5	5	0.05				—	0	0.05	V
	—	0, 10	10	0.05				—	0	0.05	
	—	0, 15	15	0.05				—	0	0.05	
Output Voltage: High-Level V_{OH} Min.	—	0, 5	5	4.95				4.95	5	—	
	—	0, 10	10	9.95				9.95	10	—	
	—	0, 15	15	14.95				14.95	15	—	
Input low Voltage, V_{IL} Max.	0.5, 4.5	—	5	1.5				—	—	1.5	
	1, 9	—	10	3				—	—	3	
	1.5, 13.5	—	15	4				—	—	4	
Input High Voltage, V_{IH} Min.	0.5, 4.5	—	5	3.5				3.5	—	—	
	1, 9	—	10	7				7	—	—	
	1.5, 13.5	—	15	11				11	—	—	
Input Current, I_{IN} Max.	—	0, 18	18	±0.1	±0.1	±1	±1	—	$\pm 10^{-5}$	±0.1	μA

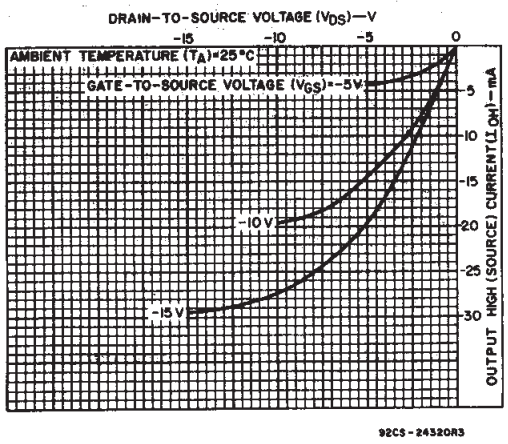


Fig. 4 — Typical output high (source) current characteristics.

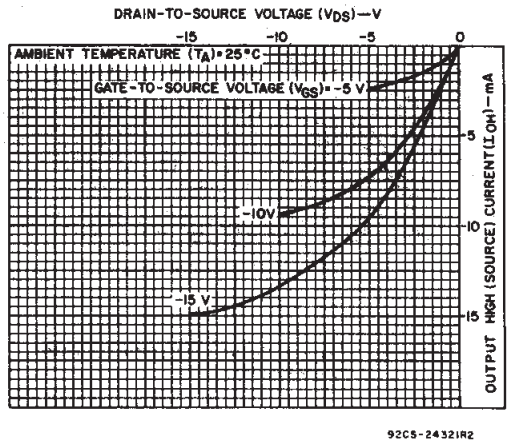


Fig. 5 — Minimum output high (source) current characteristics.

DYNAMIC ELECTRICAL CHARACTERISTICS at $T_A = 25°C$, Input t_r, $t_f = 20$ ns, $C_l = 50$ pF, R_L, $= 200$ kΩ

CHARACTERISTIC	TEST CONDITIONS	LIMITS			UNITS
	V_{DD} (V)	Min.	Typ.	Max.	
Propagation Delay Time; t_{PHL}, t_{PLH}: Clock to "Q" outputs	5	—	550	1100	ns
	10	—	225	450	
	15	—	160	320	
Clock to "0" output	5	—	420	710	ns
	10	—	160	270	
	15	—	110	190	
Clock inhibit to "Q" outputs	5	—	270	540	ns
	10	—	100	200	
	15	—	70	140	
Master reset to "Q" outputs	5	—	270	540	ns
	10	—	100	200	
	15	—	70	140	
Preset Enable Setup Time, t_{su}	5	—	0	0	ns
	10	—	0	0	
	15	—	0	0	
Preset Enable Hold Time, t_h	5	—	75	150	ns
	10	—	25	50	
	15	—	20	40	
Master Reset Removal Time, t_{rem}	5	—	130	260	ns
	10	—	50	100	
	15	—	30	60	
Transition Time, t_{THL}, t_{TLH}	5	—	100	200	ns
	10	—	50	100	
	15	—	40	80	
Minimum Pulse Width Clock, $t_{W(CL)}$	5	—	125	250	ns
	10	—	50	100	
	15	—	40	80	
Preset Enable, $t_{W(PE)}$	5	—	125	250	ns
	10	—	50	100	
	15	—	40	80	
Master Reset, $t_{W(MR)}$	5	—	175	350	ns
	10	—	125	250	
	15	—	100	200	
Max Clock Freq, f_{CL}	5	—	3	1.5	MHz
	10	—	6	3.0	
	15	—	8	4.0	
Max Clock or Clock Inhibit Rise & Fall Time, t_{TLH}, t_{THL}	5	—	—	15	us
	10	—	—	15	
	15	—	—	15	
Input Capacitance, C_{IN}	Any Input	—	5	7.5	pF

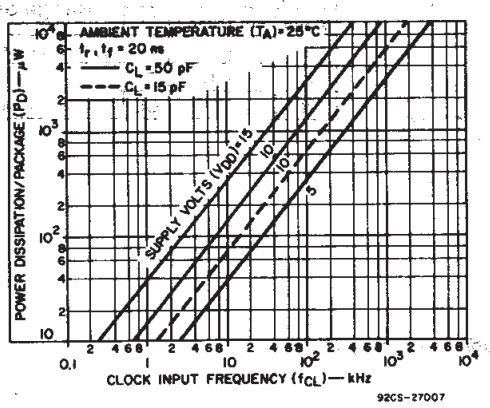
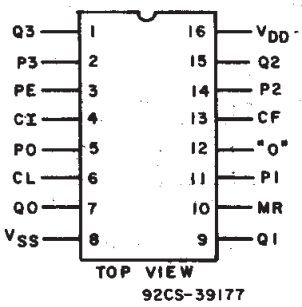


Fig. 6 — Typical dynamic power dissipation vs. frequency.



TERMINAL ASSIGNMENT

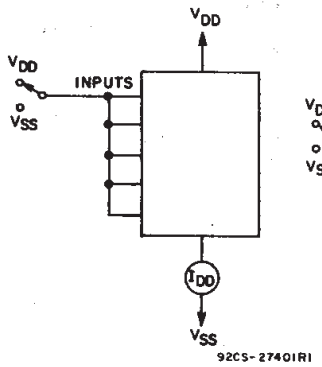


Fig. 7 — Quiescent device current test circuit.

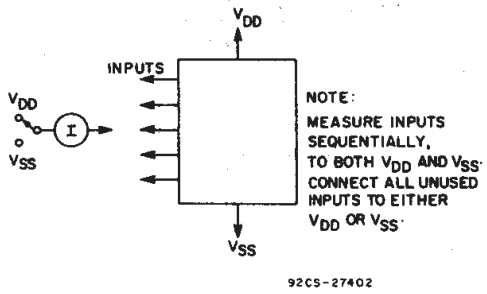


Fig. 8 — Input current test circuit.

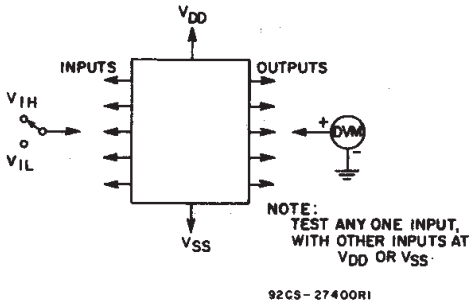
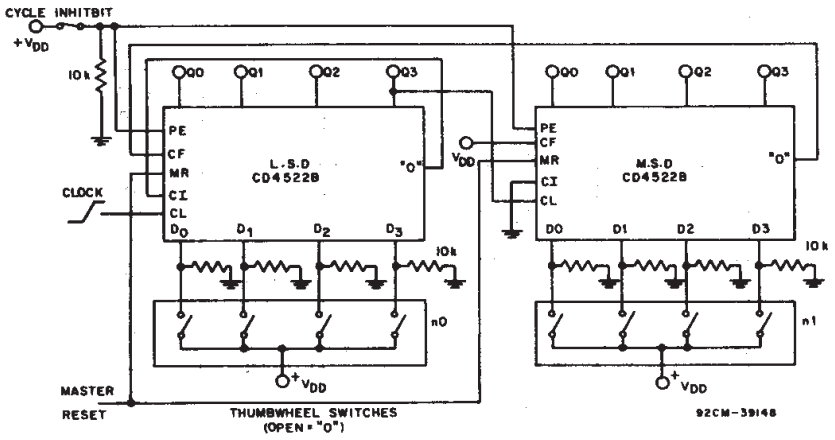


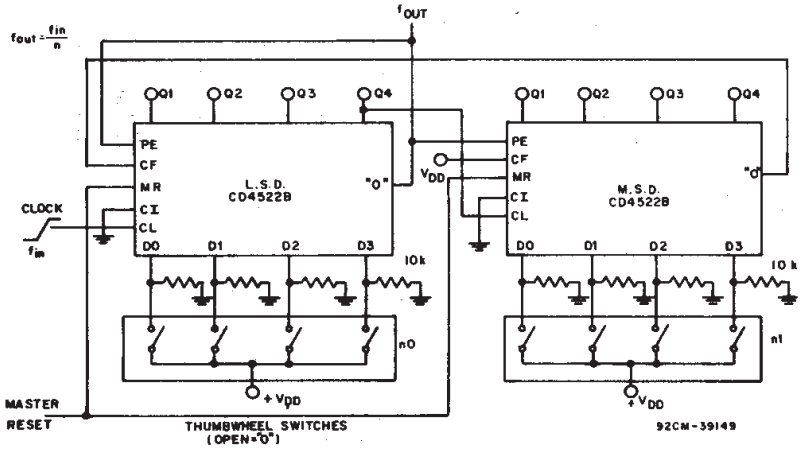
Fig. 9 — Input voltage test circuit.

APPLICATION CIRCUITS



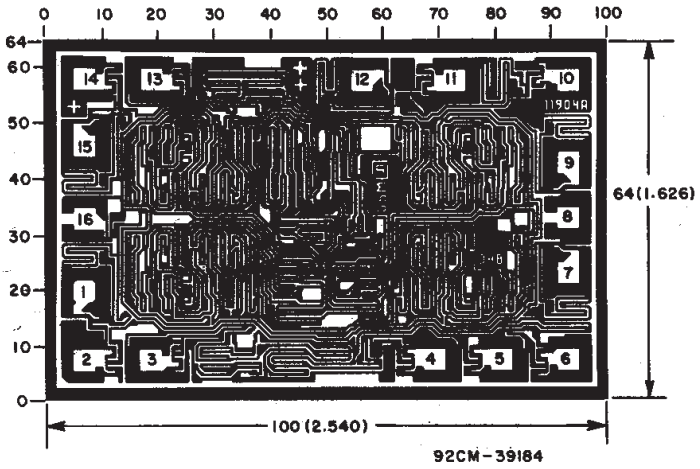
From		To		Range of N
Stage	Pin	Stage	Pin	
LSD	"0"	All	PE	LSD < N < MSD
N	"0"	N-1	CF	LSD + 1 < N < MSD
N	"0"	N+1	CL	LSD < N < MSD-1

Fig. 10 — 2-Stage Programmable Down Counter (One Cycle)



From		To		Range of N
Stage	Pin	Stage	Pin	
LSD	"0"	All	PE	LSD < N < MSD
N	"0"	N-1	CF	LSD + 1 < N < MSD
N	"0"	N+1	CL	LSD < N < MSD-1

Fig. 11 — 2-Stage Programmable Frequency Divider



Dimensions and pad layout for CD4522BH.

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch).

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
CD4522BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD4522BE	Samples
CD4522BEE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD4522BE	Samples
CD4522BM	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4522BM	Samples
CD4522BME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4522BM	Samples
CD4522BMG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4522BM	Samples
CD4522BMT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4522BM	Samples
CD4522BMTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4522BM	Samples
CD4522BMTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4522BM	Samples
CD4522BPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM522B	Samples
CD4522BPWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM522B	Samples
CD4522BPWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM522B	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

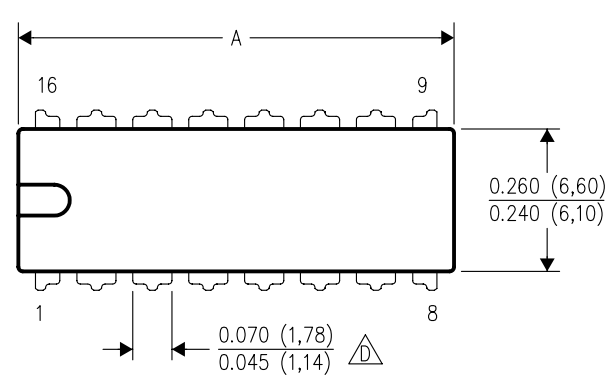
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

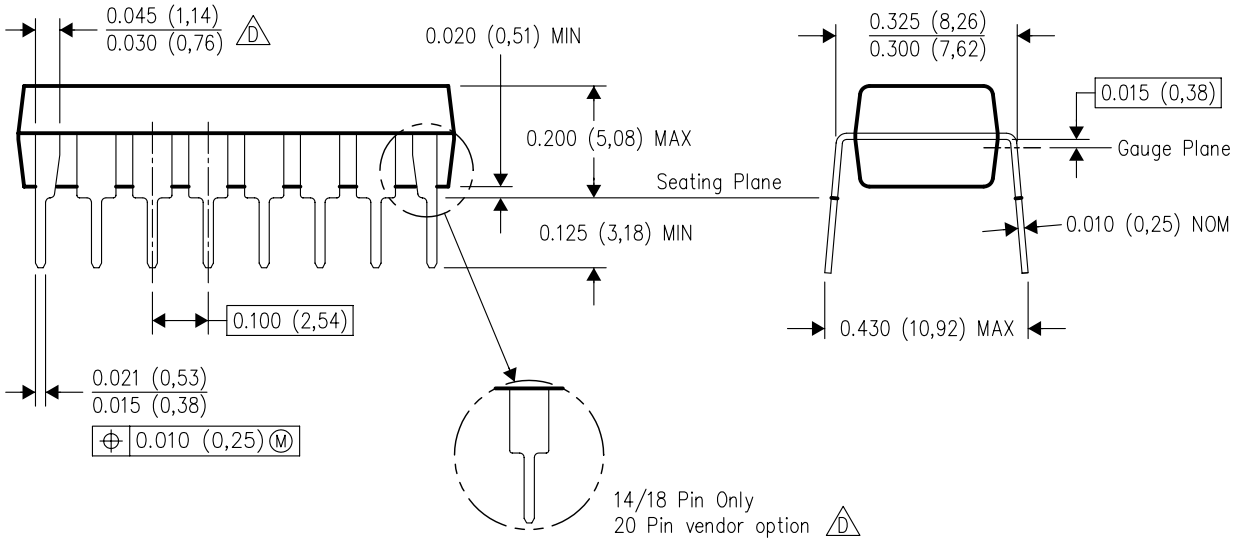
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



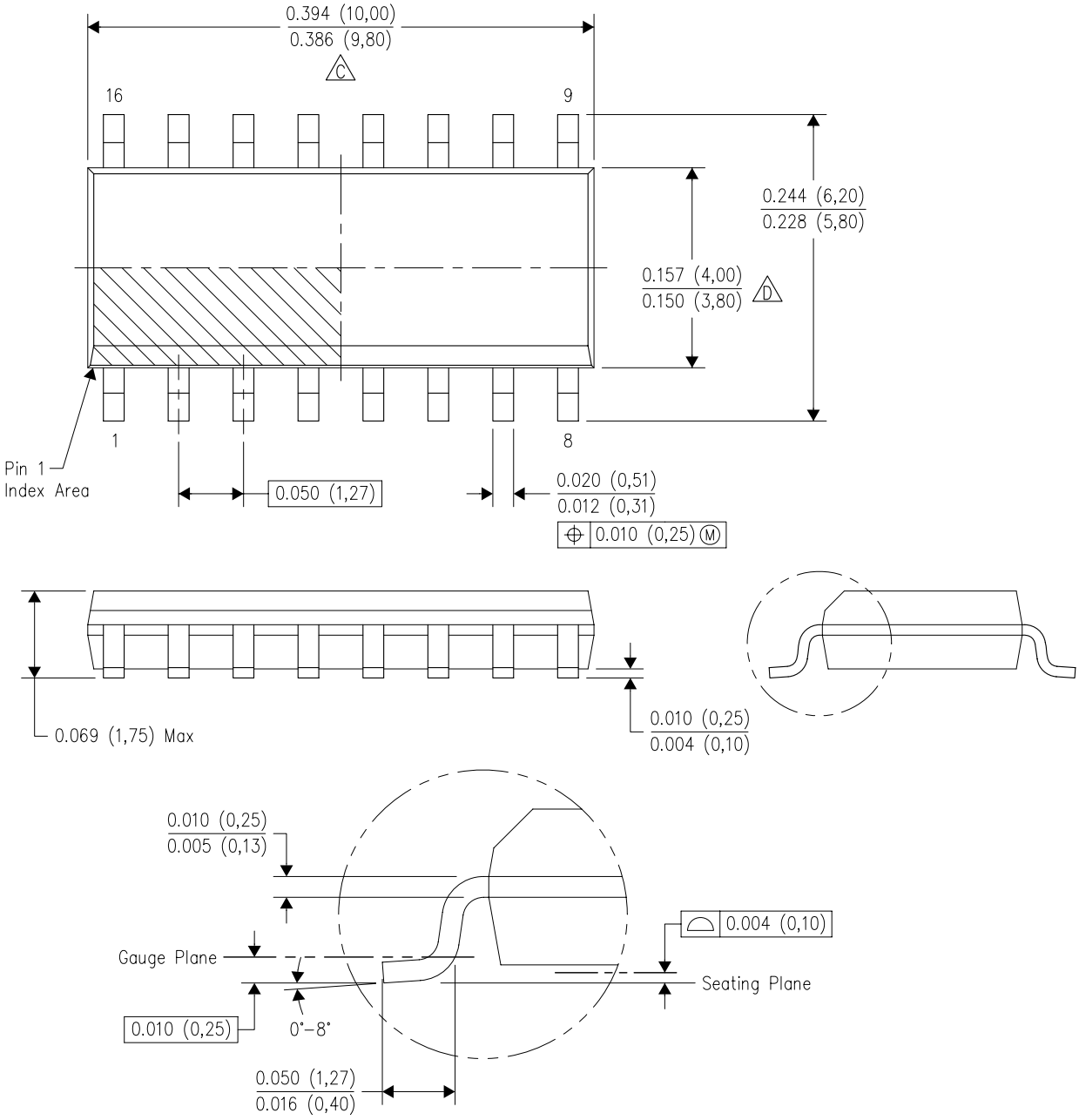
DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

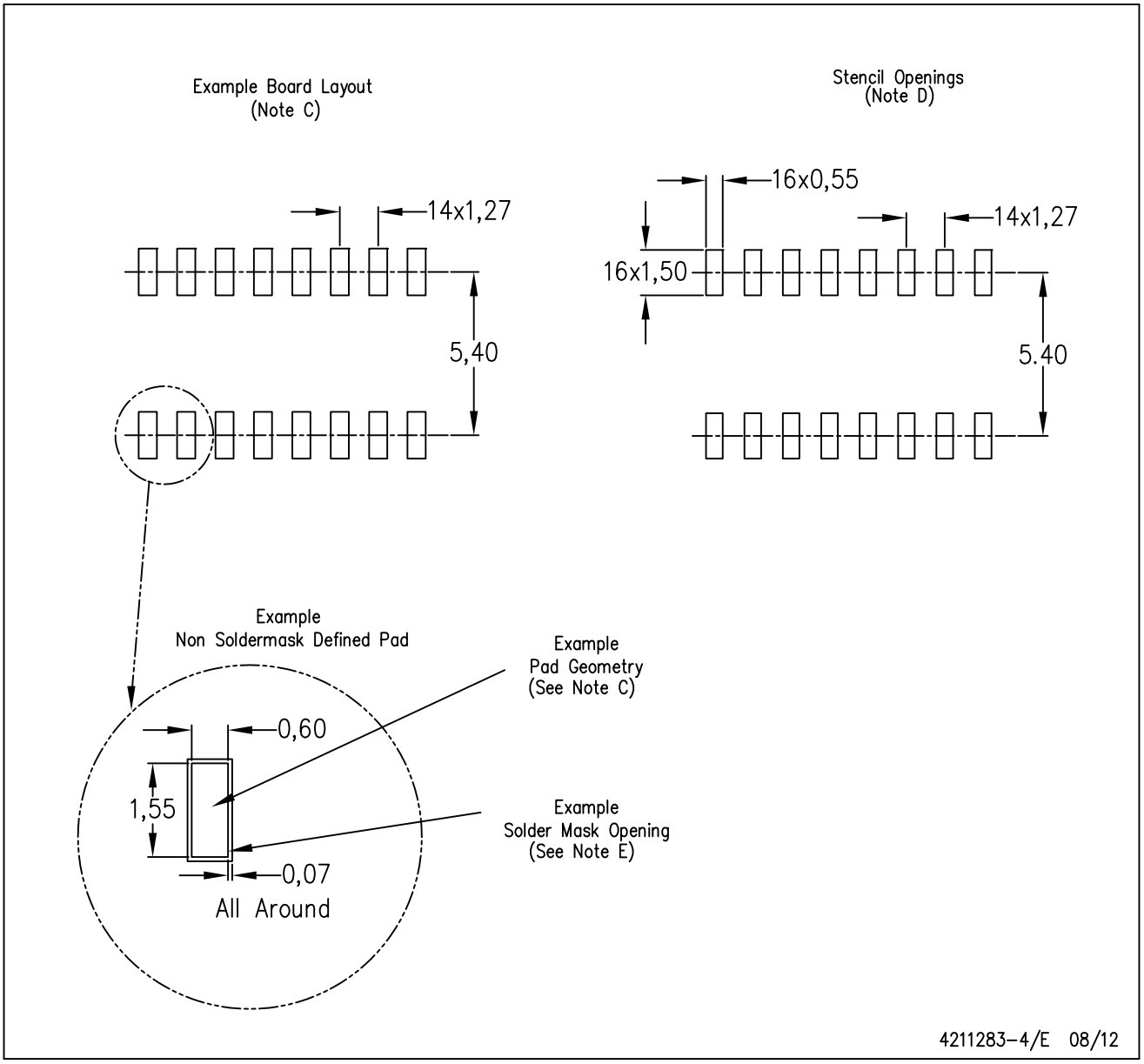
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



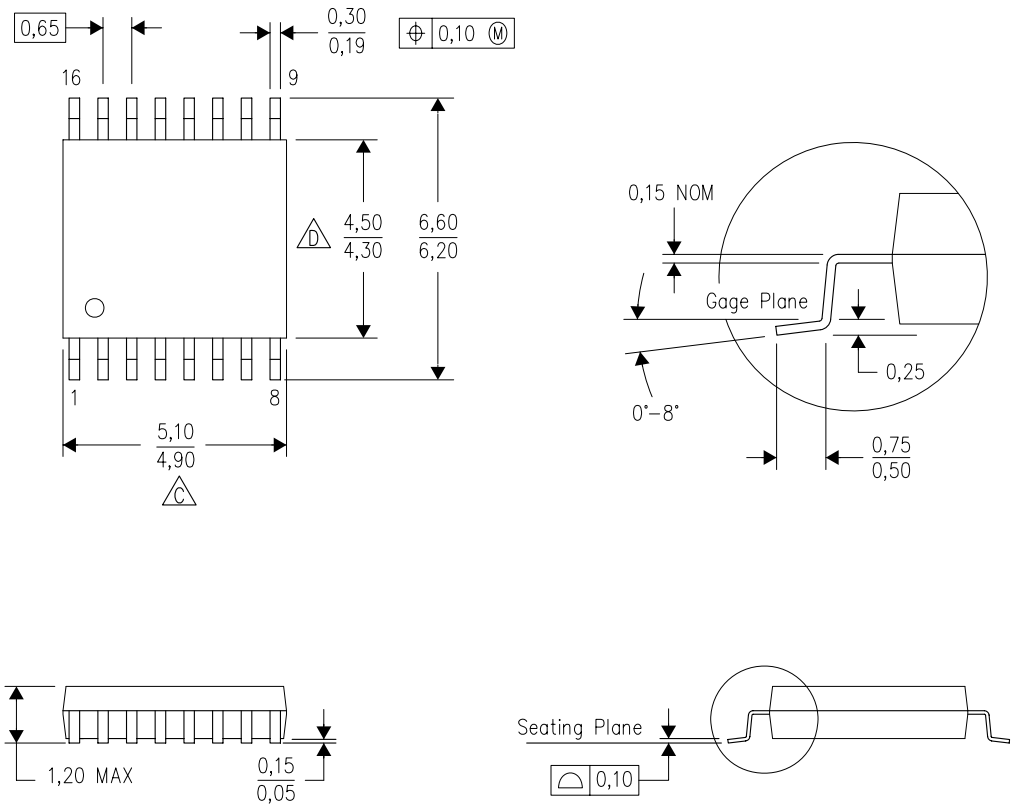
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

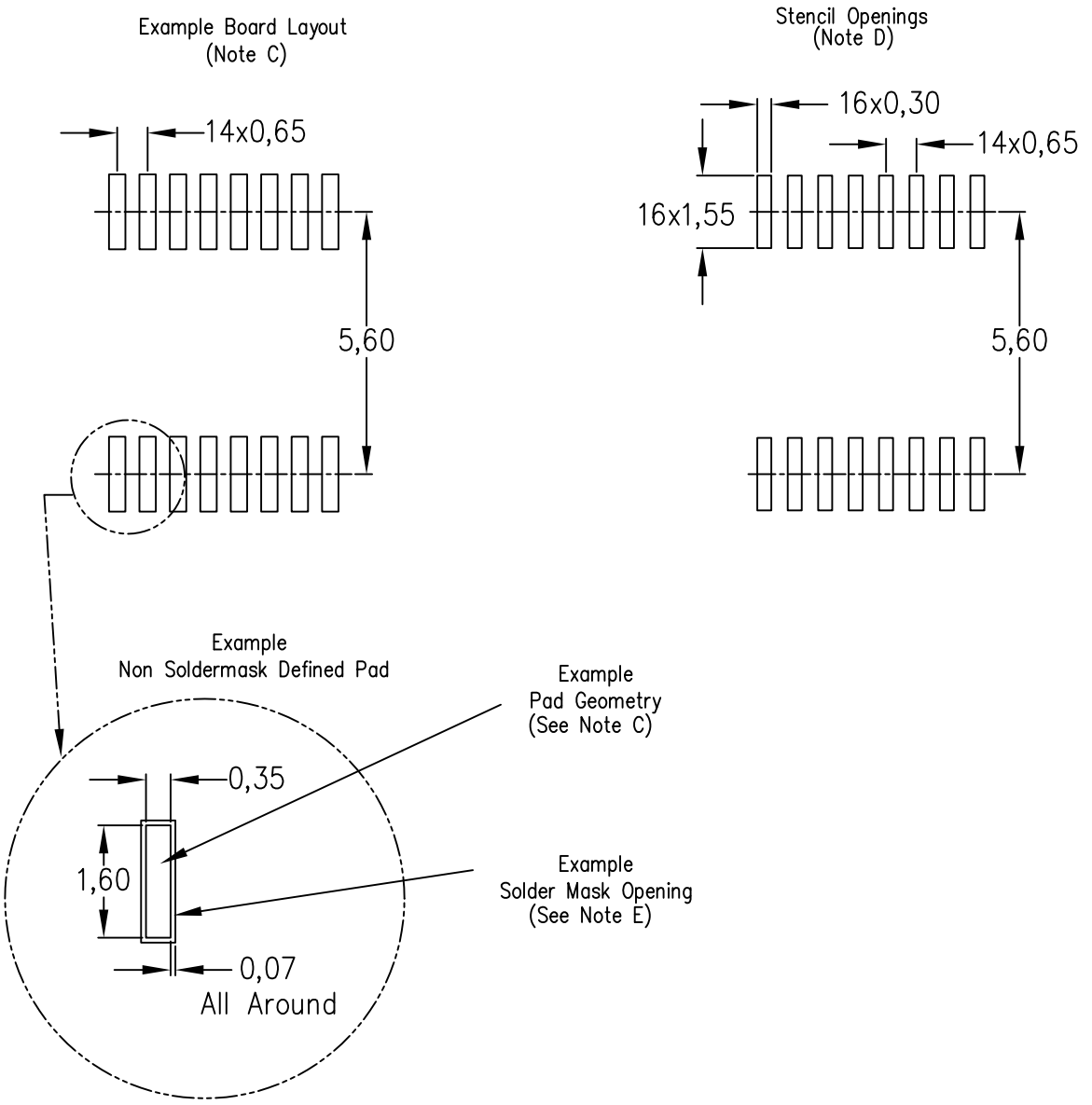
PW (R–PDSO–G16) PLASTIC SMALL OUTLINE



4040064–4/G 02/11

NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
E. Falls within JEDEC MO–153

PW (R–PDSO–G16) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as “components”) are sold subject to TI’s terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI’s terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers’ products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers’ products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI’s goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or “enhanced plastic” are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have ***not*** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products		**Applications**	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	**TI E2E Community**	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconnectivity		

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265